

CPE 1500

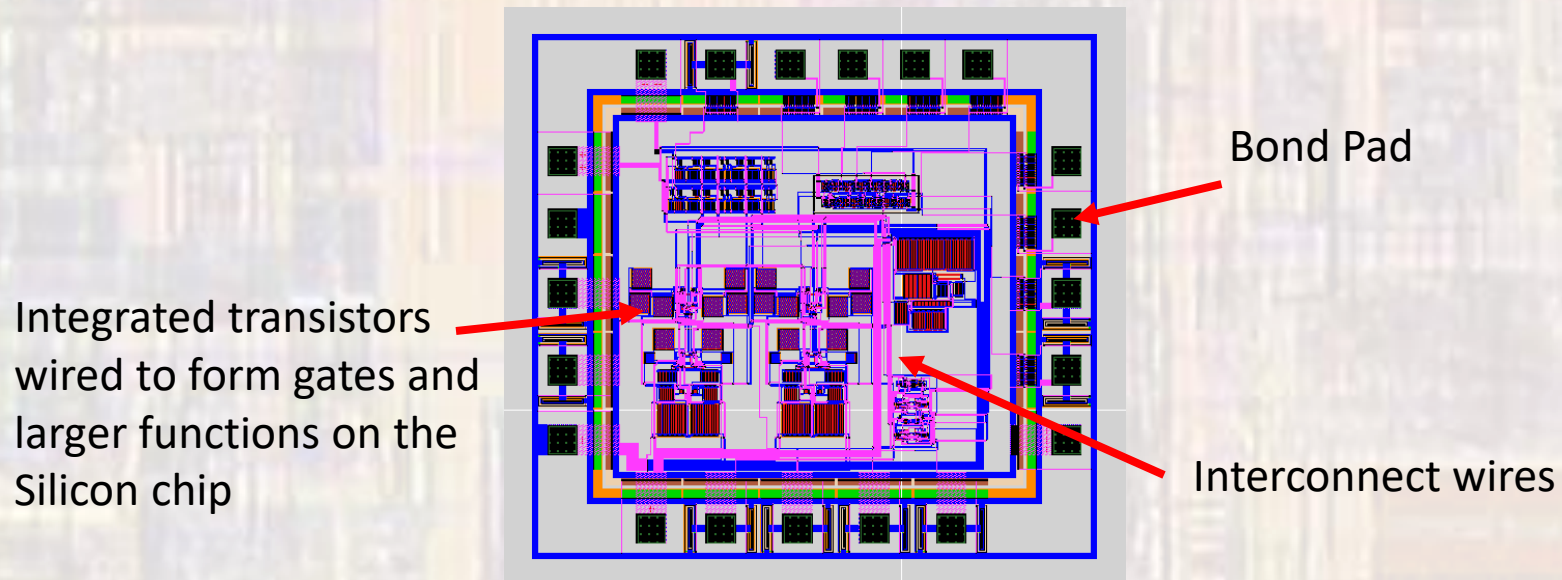
IC Package Technology

Last updated 12/16/24

CPE 1500 IC Package Technology

- Small Scale Integrated circuits – SSI C
 - 10s to 100s of gates integrated onto a Silicon wafer
 - Bond pads used to connect off the ‘chip’

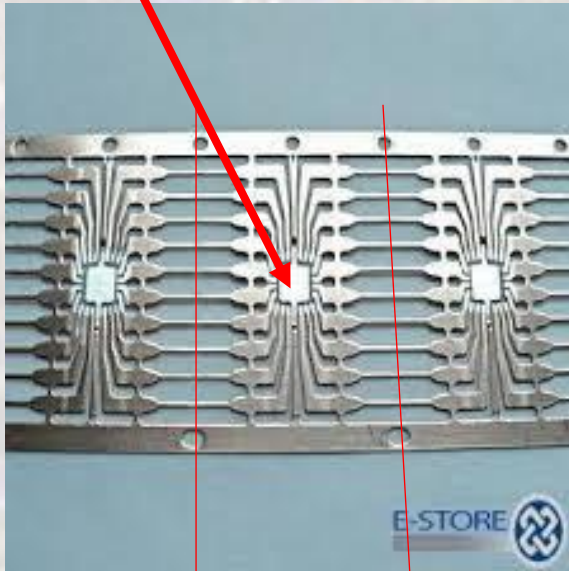
SSIC



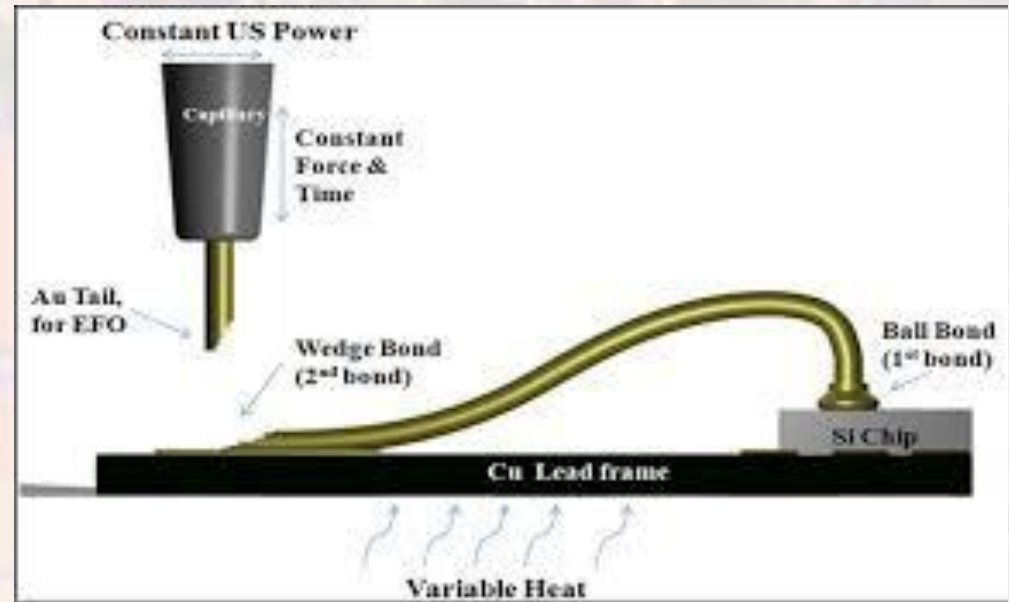
CPE 1500 IC Package Technology

- Lead Frame and Wire Bond

Chip goes here

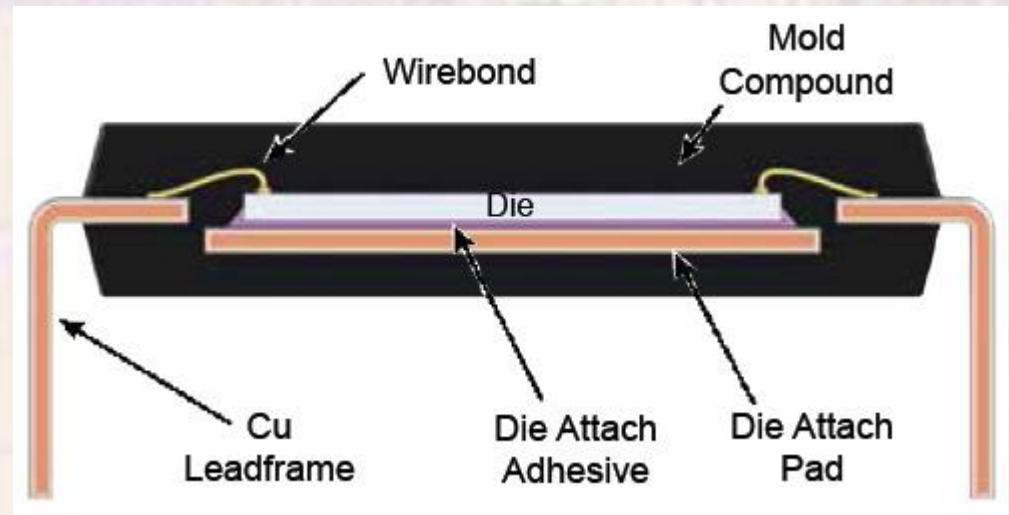


leads cut here



CPE 1500 IC Package Technology

- PDIP – Plastic Dual Inline Package



CPE 1500 IC Package Technology

- Through Hole board mounting
 - Leads pass through the PCB and are soldered on the bottom
 - Can also be inserted into a breadboard



CPE 1500 IC Package Technology

- DE10
 - Utilizes VLSI technology
 - Very Large Scale Integrated circuit technology
 - >1M transistors built on the Silicon wafer